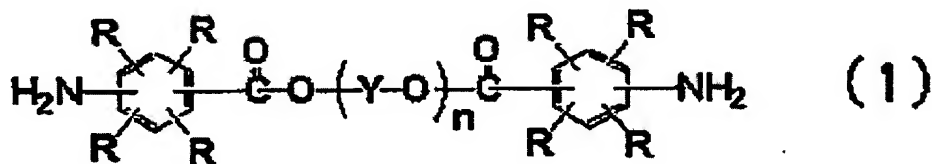


AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

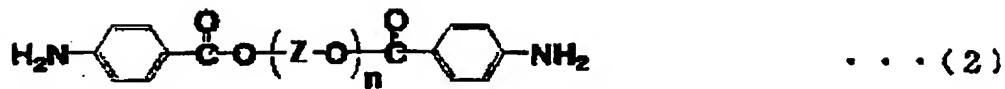
LISTING OF CLAIMS:

1. (Original) An adhesive resin composition comprising:
a thermoplastic polyimide obtained by reacting a diamine component comprising a diamine represented by the following general formula (1) with a tetracarboxylic acid dianhydride, and
a thermosetting resin contained in the ratio of from 1 to 200 weight parts, based on 100 weight parts of the thermoplastic polyimide,



wherein, in the formula (1), Rs are each independently an atom or a group selected from a group comprising a hydrogen atom, a halogen atom and a hydrocarbon group; n is a positive number of 1 to 50 on an average; Y represents an unsubstituted or substituted divalent organic group having 2 to 10 carbons; and Ys may be the same or different when n is not less than 2.

2. (Original) The adhesive resin composition according to claim 1, wherein the diamine represented by the general formula (1) is a diamine represented by the following general formula (2),



wherein, in the formula (2), n is an integer of 1 to 50 on an average; Z represents an alkylene group having 2 to 10 carbons; Zs may be the same or different when n is not less than 2.

3. (Original) The adhesive resin composition according to claim 1, wherein the diamine represented by the general formula (1) is contained in the amount of not less than 20 mole % in the total diamine components.

4. (Currently Amended) An adhesive in the form of a film comprising the adhesive resin composition as claimed in ~~any one of claims 1 to 3~~ claim 3.

5. (Original) A semiconductor device with semiconductor elements attached using the adhesive in the form of a film as claimed in claim 4.

6. (New) An adhesive in the form of a film comprising the adhesive resin composition as claimed in claim 2.

7. (New) A semiconductor device with semiconductor elements attached using the adhesive in the form of a film as claimed in claim 6.

8. (New) An adhesive in the form of a film comprising the adhesive resin composition as claimed in claim 1.

9. (New) A semiconductor device with semiconductor elements attached using the adhesive in the form of a film as claimed in claim 8.